

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

**Claims 1-5 (canceled).**

**Claim 6 (withdrawn):** A process for fabricating a composite device of the laminate type having a laminate structure of a first ceramic layer and a second ceramic layer, each of the ceramic layers having one or a plurality of circuit element patterns formed on a surface thereof to provide an electronic circuit for performing a predetermined function, the process having the steps of;

preparing one or more first green sheets for making a first ceramic portion, said one or more first green sheets comprising a dielectric material,

preparing one or more second green sheets for making a second ceramic portion, comprising

preparing material sheets by using the dielectric material,

forming a photoresist film on the surface of the material sheet prepared in the

preparing step,

providing on the photoresist film a plurality of through holes approximately uniformly

distributed by the photolithography method,

superposing magnetic material on the material sheet covering the photoresist film,

and

removing the photoresist film,

forming one or more circuit element patterns on a surface of each of said one or more first green sheets and on each of one or more second green sheets,

preparing a laminate comprising superposing said one or more first green sheets and said one or more second green sheets, and

firing the laminate to produce said composite laminate device.

**Claim 7 (withdrawn):** A process for fabricating a composite device of the laminate type having a laminate structure of a first ceramic layer and a second ceramic layer, each of the ceramic layers having one or a plurality of circuit element patterns formed on a surface thereof to provide an electronic circuit for performing a predetermined function, the process having the steps of;

preparing first green sheets for making first ceramic layers and second green sheets for making second ceramic layers,

forming one or a plurality of circuit element patterns on a surface of each of a required number of the first green sheets and a required number of the second green sheets,

preparing a laminate comprising a plurality of layers by superposing the first green sheets and the second green sheets each having the circuit element pattern or patterns formed thereon, and

firing the laminate,

the first green sheet being prepared by using dielectric material in the sheet preparing steps, the second green sheet preparing steps having:

preparing material sheets by using the dielectric material,  
providing on each of the material sheets a screen having a plurality of through holes approximately uniformly distributed, and printing magnetic material on a surface of each of material sheets through the screen, and  
removing the screen from the material sheet.

**Claim 8 (withdrawn):** A process for fabricating a composite device of the laminate type having a laminate structure of a first ceramic layer and a second ceramic layer, each of the ceramic layers having one or a plurality of circuit element patterns formed on a surface thereof to provide an electronic circuit for performing a predetermined function, the process having the steps of;

preparing first green sheets for making first ceramic layers and second green sheets for making second ceramic layers,

forming one or a plurality of circuit element patterns on a surface of each of a required number of the first green sheets and a required number of the second green sheets,

preparing a laminate comprising a plurality of layers by superposing the first green sheets and the second green sheets each having the circuit element pattern or patterns formed thereon, and  
firing the laminate,

the first green sheet being prepared by using dielectric material in the sheet preparing steps,  
the second green sheet preparing steps having:

preparing a slurry made from dielectric material,

mixing the slurry with a plurality of strips made from the magnetic material to obtain a slurry mixture,

forming the slurry mixture into a strip,

drying the obtained slurry mixture of a strip.

**Claim 9 (new):** A laminate device for use in electronic devices, comprising:

a first ceramic portion comprising one or more first layers, each of said first layers comprising

a first material, and

one or more circuit element patterns formed on a surface of said first layer; and

a second ceramic portion provided on said first ceramic portion, said second ceramic portion comprising one or more second layers, each of said second layers comprising

said first material,

a second material comprising a plurality of discrete portions dispersed within said first material or distributed on a surface of said first material, and

one or more circuit element patterns formed on a surface of said second layer,

wherein said one or more circuit element patterns provide an electronic circuit for performing a predetermined function, and said first ceramic portion is provided on said second ceramic portion to produce said laminate device.

**Claim 10 (new):** The laminate device according to claim 9, wherein said first material is a dielectric material and said second material is a magnetic material.

**Claim 11 (new):** The laminate device according to claim 9, wherein said discrete portions are approximately uniformly distributed on said surface of said first material.

**Claim 12 (new):** The laminate device according to claim 10, wherein said discrete portions are magnetic particles approximately uniformly distributed in said first material.

**Claim 13 (new):** A green sheet for fabricating a laminate device having a first ceramic portion and a second ceramic portion, for use in electronic devices, said green sheet comprising:

a ceramic layer comprising a first material and a second material, wherein said second material comprises a plurality of discrete portions dispersed within said first material or distributed on a surface of said ceramic layer comprising said first material.